



Date Created: 1/29/2004
Date Issued: 3/2/2004
PCN # 20040502

FORECAST CHANGE NOTIFICATION

This is to inform you that a design and/or process change will be made to the following product(s). This notification is for your information and concurrence. This is a preliminary notification. A final PCN will be issued when qualification is complete and data is available.

If you require data or samples to qualify this change, please contact **Fairchild Semiconductor within 30 days of receipt of this notification.**

If you have any questions concerning this change, please contact:

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PCN Originator

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REL Engineer

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PCN Type: Alternate Assembly/Test Location/Qualification

Effectivity

Expected 1st Device Shipment Date: 5/31/2004
Earliest Year/Work Week of Changed Product: 0423
(Note: Package marking may differ from this format)

Product ID (Description):

Affects all DMOS devices in MosFet BGA package.

Description of Change:

As part of Fairchild Semiconductor's effort to increase and secure a future available capacity and meets customer needs of a reliable 2nd source for MosFet BGA package, we are qualifying GEM Electronics Shanghai Ltd., located in Shanghai, China as an additional assembly, test and finishing subcontractor for MosFet BGA package.

This change is intended to meet additional demand for various products in these package, improve cycle time and service to customers.

These products are currently assembled and tested in Fairchild Semiconductor, Cebu, Philippines.

1. Process of Record (POR) Comparison:

PROCESS	FSCP	GEM
Wafer Fab	SL	SL
Solder Bumps	95Pb-5 Sn	95Pb-5 Sn
Leadframe Material	Cu/Eftec3S	Cu/Eftec3S
Lead Frame Type	Cu Stud, Dual Gage, Dual Strand	Cu Stud, Dual Gage, Dual Strand
Plating	NiPd	NiPd
Die Attach	SnSb8.5	SnSb8.5
Die attach temperature	285 +/- 5 deg C	285 +/- 5 deg C
Die to frame alignment (capability)	+/- 2 mils	+/- 2 mils

Effect of Change:

Qualifying GEM Electronics Shanghai will provide Fairchild Semiconductor the ability to meet the increase in customer demand in MosFet BGA package without any change in product performance, quality or reliability.

Qualification:

The qualification plan as written is intended to meet all our criteria for qualifying assembly and test sites and the overall quality and reliability of our products.

Qual/REL Plan Numbers

Qual Plan: Q20040004

From: ccskcb Date: 1/22/2004 Qual Plan: Q20040004

Requestor of Qualification: Romeo Racaza

Device: FDZ206P

Product Line: 02XD24 Product Family Code: 5T

Stress Test	High Temp	Low Temp	% Hum	PSI	Spl A	Spl C	TPT Dura	
TMCL	150	-65			77	77	77	100
								100
								500
								500
								500
								1000
								2000
								2500
PRCL	25				77	77	77	5000
								10000
HTRB	150	0	0	0	77	77	77	168
								500
								1000
HTGB	150	0	0	0	77	77	77	168
								500
								1000
HAST	130		85	2	77	77	96	
ACLV	121		100	15	77	77	96	

TOTAL 462 462

Device: FDZ299P

Product Line: 02XD24 Product Family Code: 5T

Stress Test	High Temp	Low Temp	% Hum	PSI	Spl A	Spl C	TPT Dura	
TMCL	100	-10			77	77	77	100
								100
								500
								500
								1000
								1500
								2000
								2500
PRCL	25				77	77	77	5000
								10000
HTRB	150	0	0	0	77	77	77	168
								500
								1000
HTGB	150	0	0	0	77	77	77	168
								500
								1000
HAST	130		85	2	77	77	96	
ACLV	121		100	15	77	77	96	
							96	
TOTAL					462	462		

Affected FSIDs

FDZ197P	FDZ201N	FDZ202P
FDZ203N	FDZ204P	FDZ206P
FDZ208P	FDZ209N	FDZ210P
FDZ226P	FDZ2551N	FDZ2552P
FDZ2553N	FDZ2553NZ	FDZ2554P
FDZ2554PZ	FDZ2555NZ	FDZ297P
FDZ298N	FDZ299P	FDZ3547N
FDZ5047N	FDZ7064N	FDZ7064S